

**ORGANISATION MONDIALE  
DU COMMERCE**

**ORGANIZACIÓN MUNDIAL  
DEL COMERCIO**

**WORLD TRADE ORGANIZATION**

Centre William Rappard  
Rue de Lausanne 154  
Case postale  
CH - 1211 Genève 21

Téléphone: (41 22) 739 51 11  
Ligne directe: (41 22) 739 52 52  
Téléfax: (41 22) 731 42 06  
Télex: 412 324 OMC/WTO CH  
Télégramme: OMC/WTO, GENÈVE

Référence: WLI/101

15 August 1997

**MARRAKESH AGREEMENT ESTABLISHING  
THE WORLD TRADE ORGANIZATION  
DONE AT MARRAKESH ON 15 APRIL 1994**

**GENERAL AGREEMENT ON TARIFFS AND TRADE 1994**

**CERTIFICATION OF MODIFICATIONS TO SCHEDULE LXII - ICELAND**

**TRANSMISSION OF CERTIFIED TRUE COPY**

I have the honour to furnish herewith a certified true copy of the Certification of Modifications to Schedule LXII - Iceland, dated 16 July 1997.

R. Ruggiero  
Director-General

**SCHEDULES OF TARIFF CONCESSIONS TO THE  
GENERAL AGREEMENT ON TARIFFS AND TRADE 1994**

**CERTIFICATION OF MODIFICATIONS**

**SCHEDULE LXII - ICELAND**

WHEREAS the CONTRACTING PARTIES to the General Agreement on Tariffs and Trade 1947 adopted, on 26 March 1980, a Decision on Procedures for Modification and Rectification of Schedules of Tariff Concessions (BISD 27S/25);

WHEREAS in accordance with the provisions of the above-mentioned Decision, a draft containing modifications to Schedule LXII - Iceland was communicated to all Members of the World Trade Organization in document G/MA/TAR/RS/22 on 16 April 1997;

IT IS HEREBY CERTIFIED that the modifications to Schedule LXII - Iceland are established in conformity with the above-mentioned Decision.

The annexed modifications shall become effective on 16 July 1997.

This Certification is deposited with the Director-General of the World Trade Organization, who shall promptly furnish a certified true copy to each Member of the World Trade Organization. It shall be registered in accordance with the provisions of Article 102 of the Charter of the United Nations.

DONE at Geneva this sixteenth day of July, one thousand nine hundred and ninety-seven.

R. Ruggiero

Certified true copy:

Director-General

## **SCHEDULE LXII - ICELAND**

### **Modifications**

16 July 1997

Iceland

26 March 1997

The elimination of customs duties and other duties and charges, as provided for in paragraph 2 of the Ministerial Declaration on Trade in Information Technology Products (WT/MIN(96)/16), is pursuant to the provisions set forth in paragraph 2 of the Annex to the Declaration.

HS96	Description	Base rate	Bound rate	Implementation	Present concession established INR	Concession first incorporated in a GATT Schedule	Earlier INRs ODCs
3818	Chemical elements doped for use in electronics, in form of discs, wafers or similar forms; chemical compounds doped for use in electronics.	0	0	2000			0
381800	-Chemical elements doped for use in electronics, in form of discs, wafers or similar forms; chemical compounds doped for use in electronics	0	0	2000			0
6815	Articles of stone or of other mineral substances (including carbon fibres, articles of carbon fibres and articles of peat), not elsewhere specified or included:						
ex68159909	Other:	67	0	2000			0
7017	Laboratory, hygienic or pharmaceutical glassware, whether or not graduated or calibrated						
701710	- Of fused quartz or other fused silica	29	0	2000			0
702000	Other articles of glass:						
ex70200009	Other	52	0	2000			0
8208	Knives and cutting blades, for machines or for mechanical appliances						
ex82089009	-Machines for sawing monocrystal semiconductors boules into slices or wafers	4	0	2000			0

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present concession established</u>	<u>Concession first incorporated in a GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
8419	Machinery, plant or laboratory equipment, whether or not electrically heated, for the treatment of materials by heating, cooking, roasting, distilling, rectifying, sterilising, pasteurising, steaming, drying, evaporating....	0	0	2000			0	
ex84198909	Other	0	0	2000			0	
841990	Parts:							
84199009	Other	0	0	2000			0	
8421	Centrifuges, including centrifugal dryers; filtering or purifying machinery and apparatus, for liquids or gases.							
	-Centrifuges, including centrifugal dryers:							
842119	--Other	0	0	2000			0	
ex842119	---Spin dryers for semiconductor wafer processing	0	0	2000			0	
ex842119	---Spinners for coating photographic emulsions on semiconductor wafers	0	0	2000			0	
	-Parts:							
842191	--Of centrifuges, including centrifugal dryers	0	0	2000			0	
ex842191	---Parts of spin dryers for semiconductor wafer processing	0	0	2000			0	
ex842191	--Parts for spinners for coating photographic emulsions on semiconductor wafers	0	0	2000			0	
ex842199	--Parts for spinners for coating photographic emulsions on semiconductor wafers	0	0	2000			0	
8422	Dish washing machines; machinery for cleaning or drying bottles or other containers; machinery for filling							

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present concession established</u>	<u>Concession first incorporated in a GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
84223000	Machinery for filling, closing, sealing, capsuling, or labeling bottles, cans, boxes, bags or other	0	0	2000			0	
ex842290	-Other	0	0	2000			0	
8424	Mechanical appliances (whether or not hand-operated) for projecting, dispersing or spraying liquids or powders; fire extinguishers, whether or not charged; spray guns and similar appliances; steam or sand blasting machines and similar jet projecting machines.							
ex842430	Steam or sand blasting machines and similar jet projecting machines	7	0	2000			0	
	-Other appliances:							
842489	--Other							
ex842489	---Deflash machines for cleaning and removing contaminants from the metal leads of semiconductor packages prior to the electroplating process	7	0	2000			0	
ex842489	---Spraying appliances for etching, stripping or cleaning semiconductor wafers	7	0	2000			0	
ex842489	---Spinners for coating photographic emulsions on semiconductor wafers	7	0	2000			0	
842490	-Parts							
ex842490	--Parts of spraying appliances for etching, stripping or cleaning semiconductor wafers	7	0	2000			0	
ex842490	--Parts for spinners for coating photographic emulsions on semiconductor wafers	0	0	2000			0	
8428	Other lifting, handling, loading or unloading machinery (for example, lifts, escalator, conveyors, telefericos):							

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present concession established</u>	<u>Concession first incorporated in a GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
ex842839	--Automated machines for transport, handling and storage of semicon.wafers, wafer cassettes, wafer boxes and other	9	0	2000			0	
ex84289009	--Automated machines for transport, handling and storage of semicon.wafers, wafer cassettes, wafer boxes and other	9	0	2000			0	
8431	Parts suitable for use solely or principally with the machinery of headings Nos. 8425 to 8430:							
ex843139	--Parts for automated machines for transport, handling and storage of semicon.wafers, wafer cassettes, wafer boxes and other	16	0	2000			0	
843139								
843139								
ex843149	--Other	16	0	2000			0	
8456	Machine-tools for working any material by removal of material, by laser or other light or photon beam, ultrasonic, electro-discharge, electro-chemical, electron beam, ionic-beam or plasma arc processes.							
845610	-Operated by laser or other light or photon beam processes	23	0	2000			0	
ex845610	--Machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers	23	0	2000			0	
845620	Operated by ultrasonic processes	0	0	2000			0	
845691	--Other							
845691	--For dry-etching patterns on semiconductor materials	0	0	2000			0	
845699	--Other							
ex845699	---Focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	0	0	2000			0	

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present</u> <u>concession</u> <u>established</u>	<u>Concession first</u> <u>incorporated in a</u> <u>GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
ex845699	---Apparatus for stripping or cleaning semiconductor wafer	0	0	2000			0	0
ex845699	---Machines for dry-etching patterns on semiconductor materials	0	0	2000			0	0
ex845699	---Lasercutters for cutting contacting tracks in semiconductor materials	0	0	2000			0	0
8462	Machine-tools (including presses) for working metal by forging, hammering or die-stamping; machine-tools(including presses) for working metal by bending, folding, straightening, flattening, shearing, punching or notching...	0	0	2000			0	0
8463	Other machine-tools for working metal or cermet, without removing material:	0	0	2000			0	0
8464	Machine-tools for working stone, ceramics, concrete, asbestos-cement or like mineral materials or for cold working glass.							
846410	-Sawing machines	0	0	2000			0	0
846420	-Grinding or polishing machines							
ex846420	--Grinding, polishing and lapping machines for processing of semiconductor wafers	0	0	2000			0	0
846490	-Other							
ex846490	--Dicing machines for scribing or scoring semiconductor wafers	0	0	2000			0	0
8465	Machine-tools (including machines for nailing, stapling, glueing or otherwise assembling ) for working wood, cork, bone, hard rubber, hard plastic or similar hard materials							
846599	-Other	0	0	2000			0	0

HS96	Description	Base rate	Bound rate	Implementation	Present concession established	Concession first incorporated in a GATT Schedule	Earlier INRs	ODCs
8466	Parts and accessories suitable for use solely or principally with the machines of headings Nos. 84.56 to 84.65, including work or tool holders, self-opening dieheads, dividing heads and other special attachments for machine-tools; tool holders for any type of tool for working in the hand.							
	-Other:							
846691	--For machines of heading No. 84.64	0	0	2000			0	
ex846691	---Parts of grinding, polishing and lapping machines for processing of semiconductor wafers	0	0	2000			0	
846692	--For machines of heading No. 8465	0	0	2000			0	
ex846692	--Parts for encapsulation equipment for assembly of semiconductors	0	0	2000			0	
846693	--For machines of headings Nos. 84.56 to 84.61							
ex846693	---Parts of focused ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices	0	0	2000			0	
ex846693	---Parts of machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers	23	0	2000			0	
ex846693	---Parts of machines for dry-etching patterns on semiconductor materials	0	0	2000			0	
ex846693	--Parts for dicing machines for scribing or scoring semiconductor wafers	0	0	2000			0	
ex846693	--Parts of apparatus for stripping or cleaning semiconductor wafers	0	0	2000			0	

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present concession established</u>	<u>Concession first incorporated in a GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
ex846694	--Parts for machines in heading 8462.8463	0	0	2000			0	
8469	Typewriters other than printers of heading No. 84.71, word-processing machines.							
	-Automatic typewriters and word-processing machines:							
846911	--Word-processing machines	29	0	2000			0	
8470	Calculating machines and pocket-size data recording, reproducing and displaying machines with calculating functions; accounting machines, postage-franking machines, ticket-issuing machines and similar machines, incorporating a calculating device; cash registers.							
847010	-Electronic calculators capable of operation without an external source of electric power and pocket-size data recording, reproducing and displaying machines with calculating functions	29	0	2000			0	
	-Other electronic calculating machines:							
847021	--Incorporating a printing device	29	0	2000			0	
847029	--Other	29	0	2000			0	
847030	-Other calculating machines	29	0	2000			0	
847040	-Accounting machines	29	0	2000			0	
847050	-Cash registers	29	0	2000			0	
847090	-Other	29	0	2000			0	
8471	Automatic data processing machines and units thereof; magnetic or optical readers, machines for transcribing data onto data media in coded form and machines for processing such data, not elsewhere specified or included.							
847110	-Analogue or hybrid automatic data processing machines	17	0	2000			0	

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present</u> <u>concession</u> <u>established</u>	<u>INR</u>	<u>GATT Schedule</u>	<u>Concession first</u> <u>incorporated in a</u>	<u>Earlier INRs</u>	<u>ODCs</u>
847130	-Portable digital automatic data processing machines, weighing no more than 10 kg, consisting of at least a central processing unit, a keyboard and a display	17	0	2000					0	
	-Other digital automatic data processing machines:									
847141	--Comprising in the same housing at least a central processing unit and an input and output unit, whether or not combined	17	0	2000					0	
847149	--Other, presented in the form of systems	17	0	2000					0	
847150	-Digital processing units other than those of subheadings 8471 41 and 8471 49, whether or not containing, in the same housing one or two of the following types of unit: storage units, input units, output units	17	0	2000					0	
ex847160	-Input or output units, whether or not containing storage units in the same housing	17	0	2000					0	
ex847160	Ink-jet printing machine	17	0	2000					0	
847170	-Storage units	17	0	2000					0	
847180	-Other units of automatic data processing machines	17	0	2000					0	
847190	-Other	17	0	2000					0	
8472	Other office machines (for example, hectograph or stencil duplicating machines, addressing machines, automatic banknote dispensers, coin-sorting machines, coin-counting or wrapping machines, pencil-sharpening machines, perforating or stapling machines).									
847290	-Other									
ex847290	--Automatic teller machines	29	0	2000					0	

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present concession established</u>	<u>Concession first incorporated in a GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
8473	Parts and accessories (other than covers, carrying cases and the like) suitable for use solely or principally with machines of headings Nos. 84.69 to 84.72.							
847310	-Parts and accessories of the machines of heading No. 8469	29	0	2000			0	
847321	-Parts and accessories of the machines of heading No. 84.70:							
	--Of the electronic calculating machines of subheading No. 8470.10, 8470.21 or 8470.29	24	0	2000			0	
847329	--Other	24	0	2000			0	
847330	-Parts and accessories of the machines of heading No. 84.71	0	0	2000			0	
847340	-Part and accessories of the machines of heading No 8472	0	0	2000			0	
847350	-Parts and accessories equally suitable for use with machines of two or more of the headings Nos. 84.69 to 84.72	24	0	2000			0	
8477	Machinery for working rubber or plastics or for the manufacture of products from these materials, not specified or included elsewhere in this Chapter							
847710	-Injection-moulding machines	0	0	2000			0	
847740	-Vacuum moulding machines and other thermoforming machines	0	0	2000			0	
847759	-- Other	0	0	2000			0	
847780	-Other machinery	0	0	2000			0	
847790	-Parts	0	0	2000			0	
8479	Machines and mechanical appliances having individual functions, not specified or included elsewhere in this Chapter							

<u>HS96</u>	<u>Description</u>	<u>Base rate</u>	<u>Bound rate</u>	<u>Implementation</u>	<u>Present concession established</u>	<u>Concession first incorporated in a GATT Schedule</u>	<u>Earlier INRs</u>	<u>ODCs</u>
847950	Automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices	16	0	2000			0	
	-Other machines and mechanical appliances:							
847989	--Other							
ex847989	---Apparatus for growing or pulling monocrystal semiconductor boules	16	0	2000			0	
ex847989	---Epitaxial deposition machines for semiconductor wafers	16	0	2000			0	
ex847989	---Apparatus for wet etching,developing, stripping or cleaning semiconductor wafers and flat panel displays	16	0	2000			0	
ex847989	---Encapsulation equipment for assembly of semiconductors	16	0	2000			0	
ex847989	---Machines for bending, folding and straightening semiconductors leads	16	0	2000			0	
ex847989	---Physical deposition apparatus for semiconductor production	16	0	2000			0	
ex847989	---Spinners for coating photographic emulsions on semiconductors wafers	16	0	2000			0	
ex847989	---Chemical vapor deposition apparatus for semiconductor production	16	0	2000			0	
ex847989	---Automated machines for transport,handling and storage of semicond.wafers,wafer cassettes,wafer boxes and other material for	16	0	2000			0	
ex847989	---Die attach apparatus for wet etching,tape automated bonders,and wire bonders for assembly of semiconductor	16	0	2000			0	